

HD74LS166A

8-bit Shift Register

REJ03D0450-0400
Rev.4.00
May 10, 2006

The inputs are buffered to lower the drive requirements to one series 74 or 74LS standard load, respectively. Input clamping diodes minimize switching transients and simplify system design. This parallel in or serial-in, serial-out shift register has a complexity of 77 equivalent gates on a monolithic chip. This device features gated clock inputs and an overriding clear input.

The parallel-in or serial-in modes are established by the shift / load input.

When high, this input enables the serial data input and couples the eight flip-flops for serial shifting with each clock pulse. When low, the parallel (broadside) data inputs are enabled and synchronous loading occurs on the next clock pulse, during parallel loading, serial data flow is inhibited.

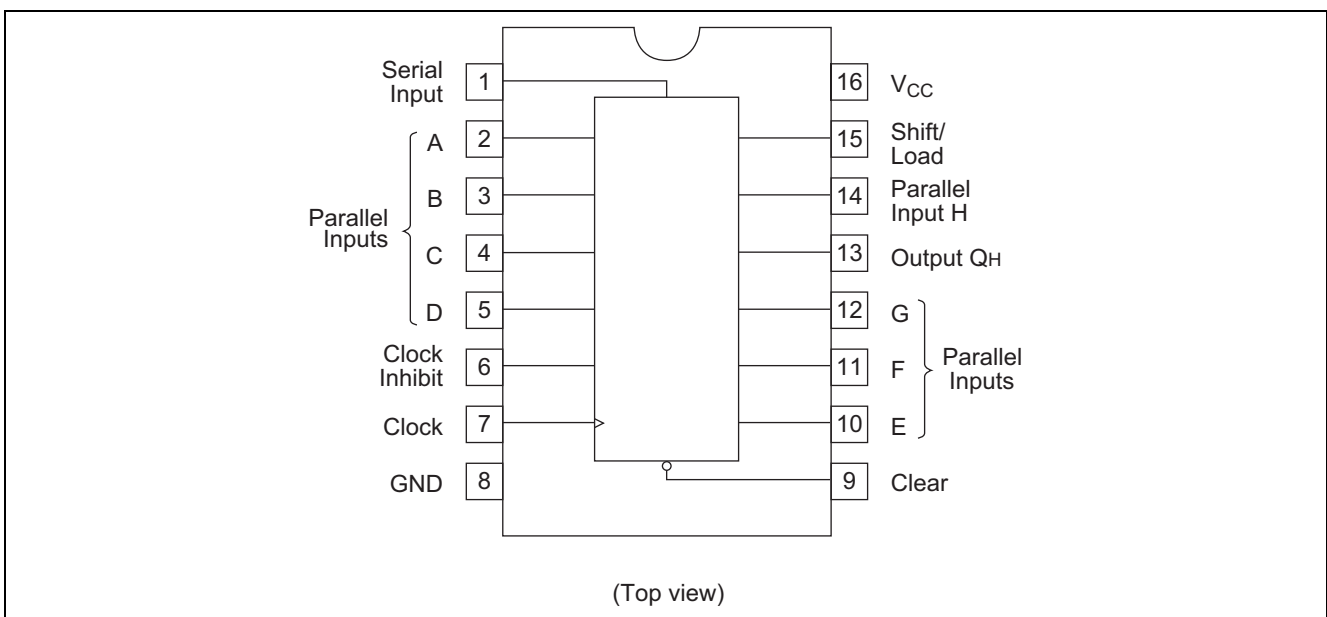
This, of course, allows the system clock to be free running and the register can be stopped on command with the other clock input. The clock-inhibit input should be changed to the high level only while the clock input is high. A buffered, direct clear input overrides all other inputs, including the clock, and sets all flip-flops to zero.

Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS166AP	DILP-16 pin	PRDP0016AE-B (DP-16FV)	P	—

Pin Arrangement

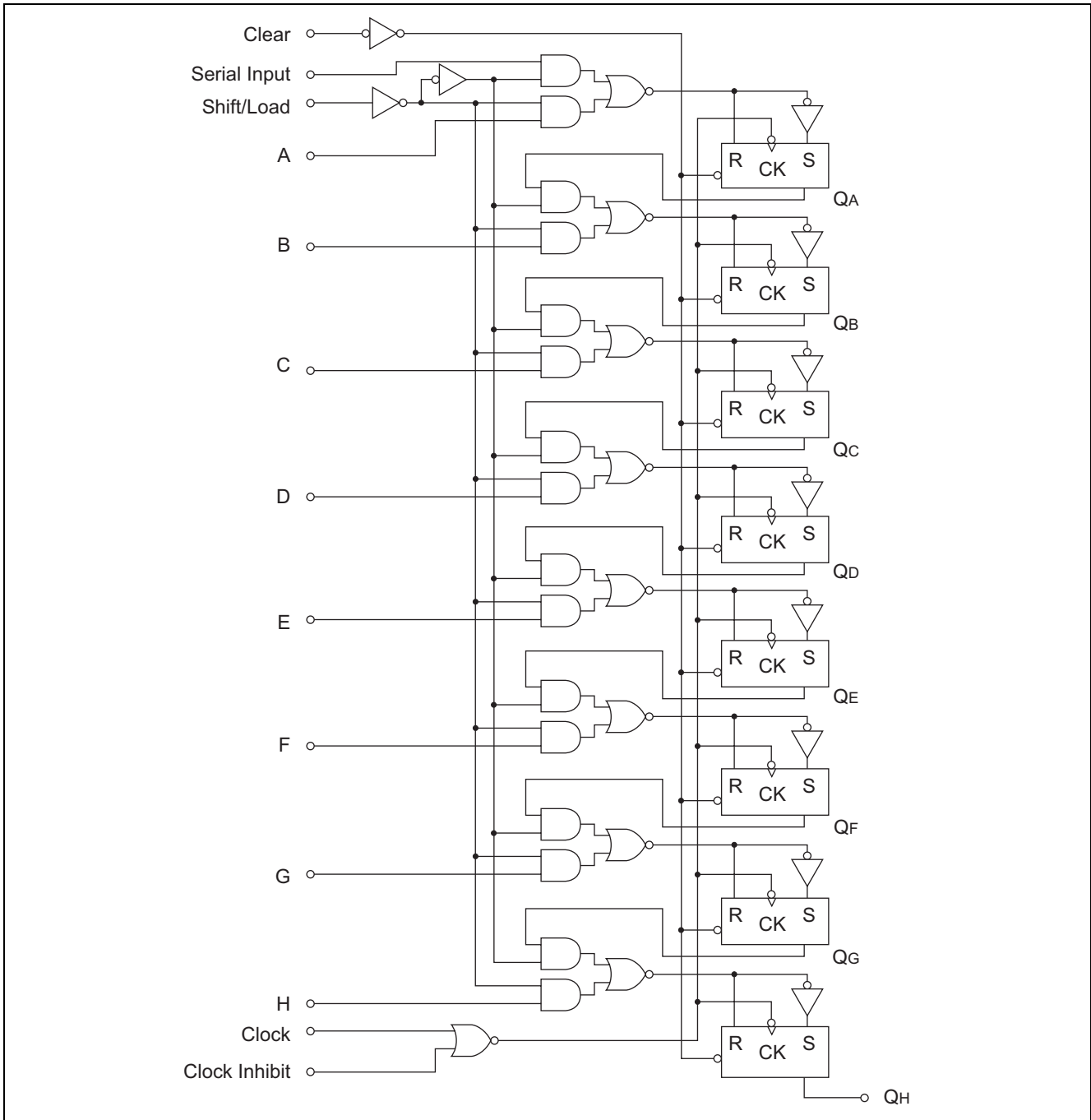


Function Table

Inputs						Internal outputs		Output Q_H
Clear	Shift Load	Clock Inhibit	Clock	Serial	Parallel	Q_A	Q_B	
					A...H			
L	X	X	X	X	X	L	L	L
H	X	L	L	X	X	Q_{A0}	Q_{B0}	Q_{H0}
H	L	L	↑	X	a...h	a	b	h
H	H	L	↑	H	X	H	Q_{An}	Q_{Gn}
H	H	L	↑	L	X	L	Q_{An}	Q_{Gn}
H	X	H	↑	X	X	Q_{A0}	Q_{B0}	Q_{H0}

- Notes:
1. H; high level, L; low level, X; irrelevant
 2. ↑; transition from low to high level
 3. a to h; the level of steady-state input at inputs A to H respectively
 4. Q_{A0} to Q_{H0} ; the level of Q_A to Q_H , respectively, before the indicated steady-state input conditions were established.
 5. Q_{An} to Q_{Gn} ; the level of Q_A to Q_G , respectively, before the most recent ↑ transition of the clock.

Block Diagram



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC}	7	V
Input voltage	V_{IN}	7	V
Power dissipation	P_T	400	mW
Storage temperature	T_{stg}	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
Output current	I_{OH}	—	—	-400	μA
	I_{OL}	—	—	8	mA
Operating temperature	T_{opr}	-20	25	75	$^{\circ}C$
Clock frequency	f_{clock}	0	—	25	MHz
Clock and clear pulse width	t_w	20	—	—	ns
Mode control setup time	t_{su}	30	—	—	ns
Data setup time	t_{su}	20	—	—	ns
Hold time	t_h	0	—	—	ns

Electrical Characteristics

($T_a = -20$ to $+75^{\circ}C$)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V_{IH}	2.0	—	—	V	
	V_{IL}	—	—	0.8	V	
Output voltage	V_{OH}	2.7	—	—	V	$V_{CC} = 4.75$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V, $I_{OH} = -400$ μA
	V_{OL}	—	—	0.4	V	$V_{CC} = 4.75$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V
		—	—	0.5		
Input current	I_{IH}	—	—	20	μA	$V_{CC} = 5.25$ V, $V_I = 2.7$ V
	I_{IL}	—	—	-0.4	mA	$V_{CC} = 5.25$ V, $V_I = 0.4$ V
	I_I	—	—	0.1	mA	$V_{CC} = 5.25$ V, $V_I = 7$ V
Short-circuit output current	I_{OS}	-20	—	-100	mA	$V_{CC} = 5.25$ V
Supply current**	I_{CC}	—	20	32	mA	$V_{CC} = 5.25$ V
Input clamp voltage	V_{IK}	—	—	-1.5	V	$V_{CC} = 4.75$ V, $I_{IN} = -18$ mA

Notes: * $V_{CC} = 5$ V, $T_a = 25^{\circ}C$

** With the outputs open, 4.5 V applied to the serial input and all other inputs except the clock grounded, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.

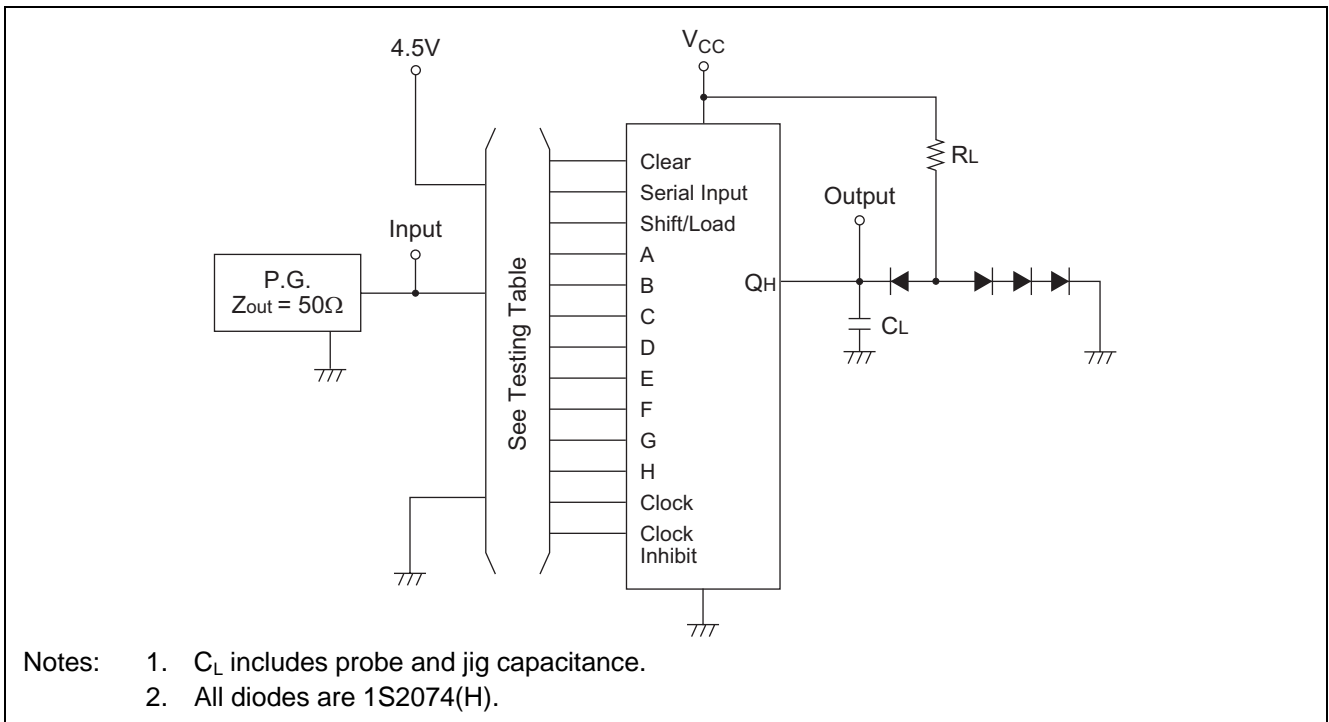
Switching Characteristics

($V_{CC} = 5$ V, $T_a = 25^{\circ}C$)

Item	Symbol	Inputs	min.	typ.	max.	Unit	Condition
Maximum clock frequency	f_{max}		25	35	—	MHz	$C_L = 15$ pF, $R_L = 2$ k Ω
Propagation delay time	t_{PHL}	Clear	—	19	30	ns	
	t_{PHL}	Clock	7	14	25	ns	
	t_{PLH}		5	11	20	ns	

Testing Method

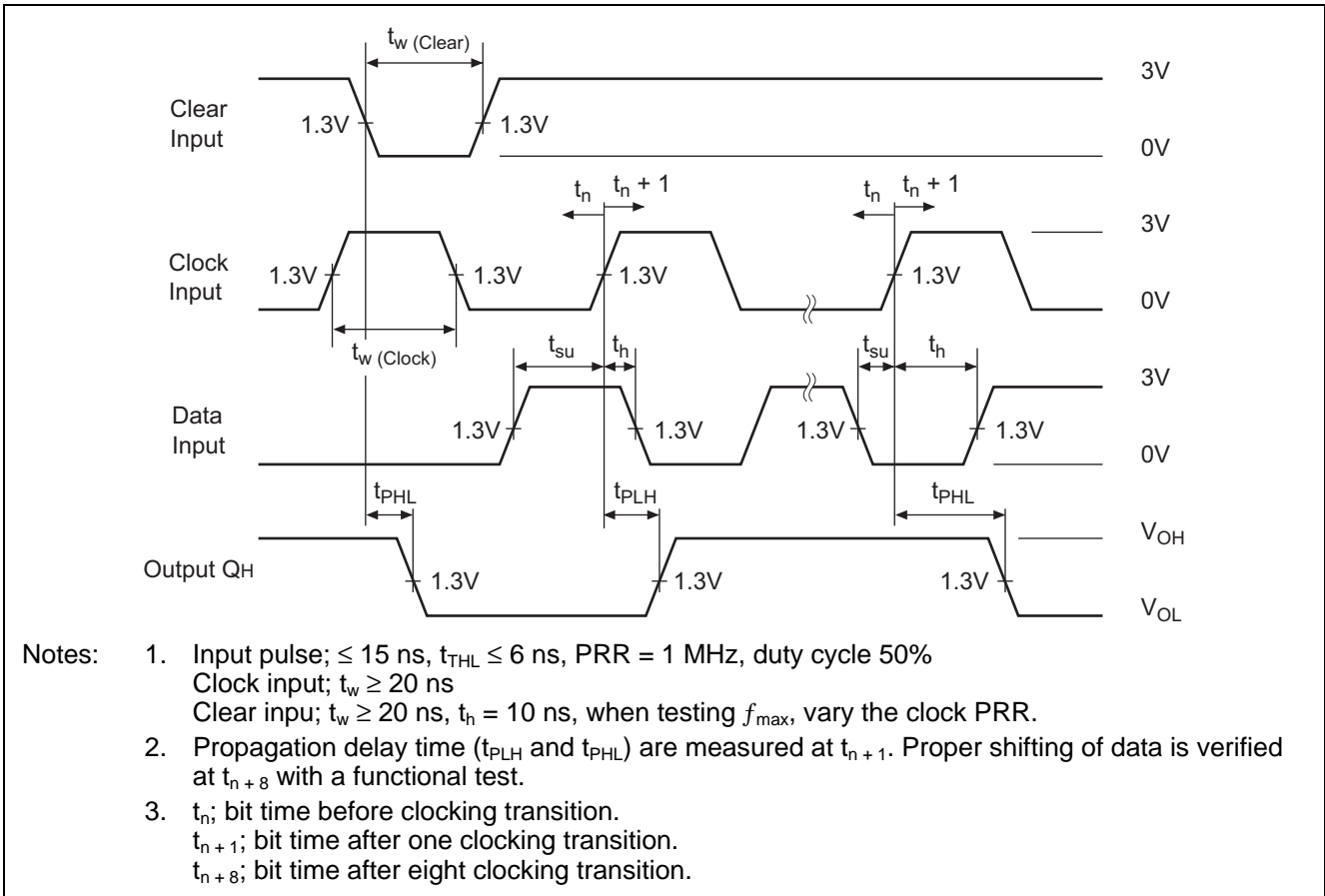
Test Circuit



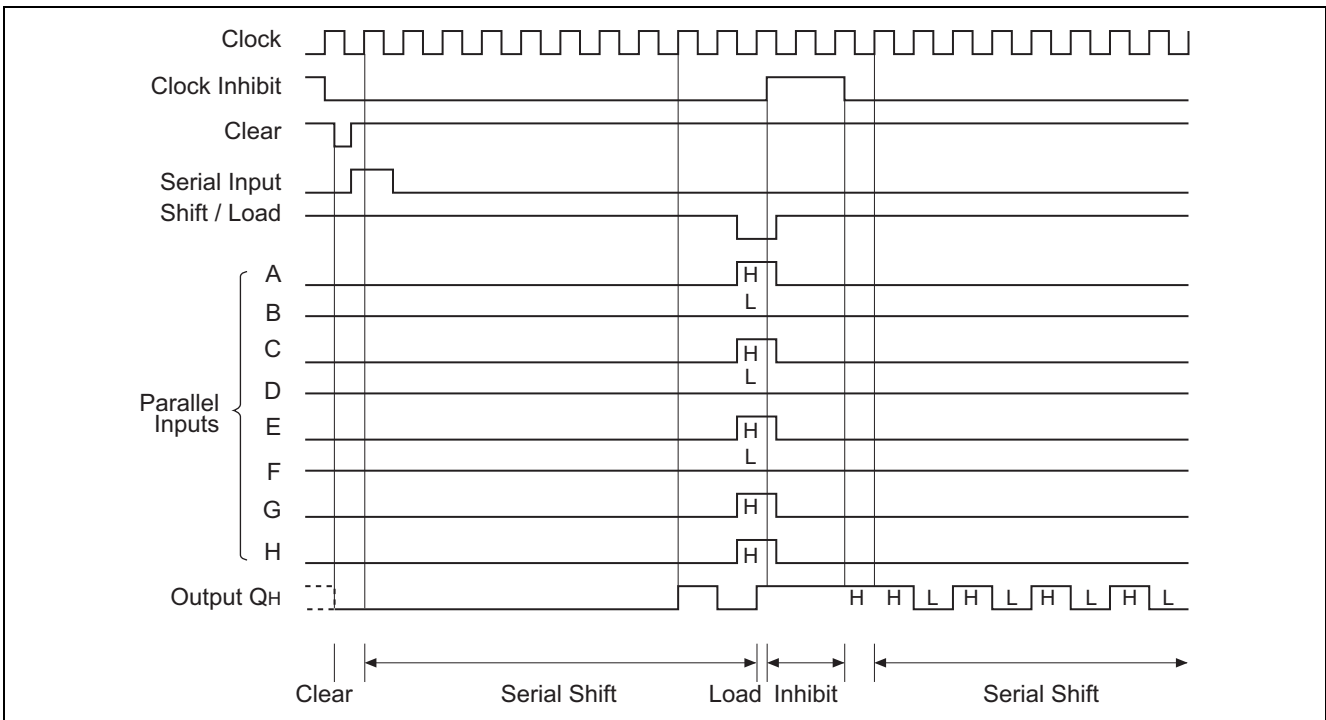
Testing table

Data inputs	Shift / Load	Output	Bit time
Data H	0 V	Q_H	t_{n+1}
Serial-in	4.5 V	Q_H	t_{n+8}

Waveform

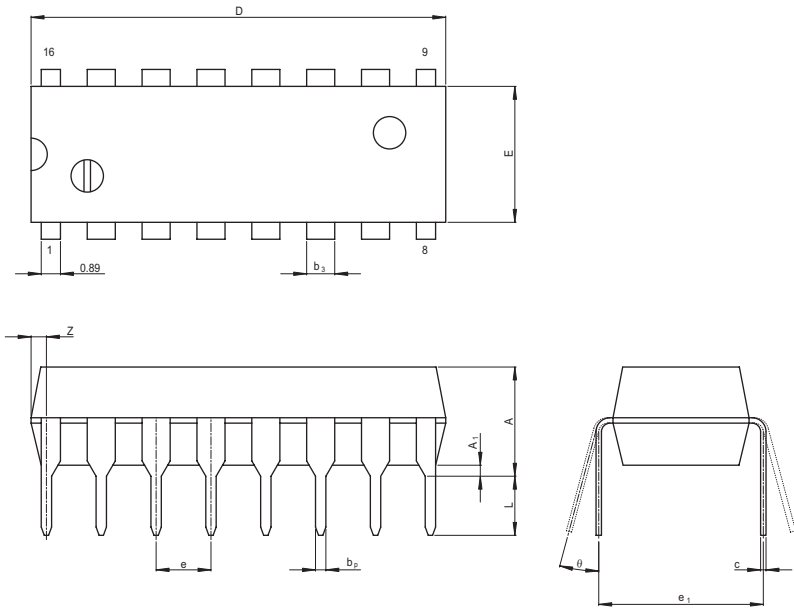


Typical Clear, Shift, Load, Inhibit, and Shift Sequences



Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-DIP16-6.3x19.2-2.54	PRDP0016AE-B	DP-16FV	1.05g



(NiPd/Au plating)

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e_1	—	7.62	—
D	—	19.2	20.32
E	—	6.3	7.4
A	—	—	5.06
A_1	0.51	—	—
b_p	0.40	0.48	0.56
b_3	—	1.30	—
c	0.19	0.25	0.31
θ	0°	—	15°
e	2.29	2.54	2.79
Z	—	—	1.12
L	2.54	—	—

Keep safety first in your circuit designs!

1. Renesas Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.
Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corp. or a third party.
 2. Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
 3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for the latest product information before purchasing a product listed herein.
The information described here may contain technical inaccuracies or typographical errors.
Renesas Technology Corp. assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.
Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (<http://www.renesas.com>).
 4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
 5. Renesas Technology Corp. semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
 6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce in whole or in part these materials.
 7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
 8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.
-



RENESAS SALES OFFICES

<http://www.renesas.com>

Refer to "<http://www.renesas.com/en/network>" for the latest and detailed information.

Renesas Technology America, Inc.

450 Holger Way, San Jose, CA 95134-1368, U.S.A
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd.

Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7898

Renesas Technology Hong Kong Ltd.

7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.

10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology Singapore Pte. Ltd.

1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.

Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510